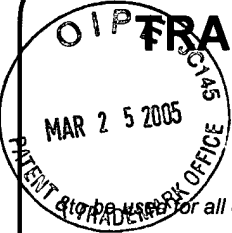


Please type a plus sign (+) inside this box ☐Approved for use through 10/31/02. OMB 0651-0031  
U.S. Patent and Trademark Office; U.S. DEPARTMENT OF COMMERCE

Under the Paperwork Reduction Act of 1995, no persons are required to respond to a collection of information unless it displays a valid OMB control number.

|  |                    |                               |
|--|--------------------|-------------------------------|
|  | Application Number | 10/813,407                    |
|  | Filing Date        | March 29, 2004                |
|  | First Inventor     | Jiping Li                     |
|  | Confirmation No.   | 5642                          |
|  | Group Art Unit     | 2811                          |
| Examiner Name  |                    | Unknown                       |
| Total Number Of Pages In This Submission   | 8                  | Attorney Docket No. BOX016 US |

## ENCLOSURES (check all that apply)


- |  |   |   |
|--|---|---|
| <input type="checkbox"/> Fee Transmittal Form<br>(1 page in duplicate)         | <input type="checkbox"/> Assignment Papers<br>(for an Application)  | <input type="checkbox"/> After Allowance Communication to Group                               |
| <input type="checkbox"/> Fee Attached -- Credit Card Payment Form (1 pg)       | <input type="checkbox"/> Drawing(s)   | <input type="checkbox"/> Appeal Communication to Board of Appeals and Interferences           |
| <input type="checkbox"/> Amendment / Reply                                     | <input type="checkbox"/> Licensing-related Papers   | <input type="checkbox"/> Appeal Communication to Group<br>(Appeal Notice, Brief, Reply Brief) |
| <input type="checkbox"/> After Final   | <input type="checkbox"/> Petition   | <input type="checkbox"/> Proprietary Information  |
| <input type="checkbox"/> Affidavits/declarations                               | <input type="checkbox"/> Petition to Convert to a Provisional Application                                     | <input type="checkbox"/> Status Letter  |
| <input type="checkbox"/> Extension of Time Request                             | <input type="checkbox"/> Power of Attorney, Revocation of Previous Powers; And Statement Under 37 CFR 3.73(b) | <input checked="" type="checkbox"/> Other Enclosure(s) (please identify below):               |
| <input type="checkbox"/> Express Abandonment Request                           | <input type="checkbox"/> Terminal Disclaimer  |   |
| <input checked="" type="checkbox"/> Information Disclosure Statement (2 pages) | <input type="checkbox"/> Request for Refund   |   |
| <input type="checkbox"/> Certified Copy of Priority Document(s)                | <input type="checkbox"/> CD, Number of CD(s) _____  |   |

RETURN RECEIPT POSTCARD  
PTO Form 1449 (5 pages)  
Copies of 50 cited references

Remarks

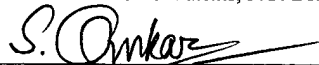
Please charge Deposit Account 50-2263 for any underpaid fee.

## SIGNATURE OF APPLICANT, ATTORNEY OR AGENT

|                         |   |
|-------------------------|---|
| Firm or Individual Name | Omkar K. Suryadevara (Reg. No. 36,320)<br>Silicon Valley Patent Group LLP<br>2350 Mission College Boulevard, Suite 360<br>Santa Clara, California 95054 |
| Signature               |    |
| Date                    | March 23, 2005  |

## CERTIFICATE OF MAILING BY "FIRST CLASS"

I hereby certify that this paper or fee is being deposited with the United States Postal Service with sufficient postage as first class mail in an envelope addressed to: Commissioner for Patents, P.O. Box 1450, Alexandria, VA 22313-1450 on the below date.

  
 Omkar K. Suryadevara

 March 23, 2005  
 Date

Burden Hours Statement: This form is estimated to take 0.2 hours to complete. Time will vary depending upon the needs of the individual case. Any comments on the amount of time you are required to complete this form should be sent to the Chief Information Officer, U.S. Patent and Trademark Office, P.O. Box 1450, Arlington, VA 22313-1450. DO NOT SEND FEES OR COMPLETED FORMS TO THIS ADDRESS. SEND TO: Commissioner for Patents, P.O. Box 1450, Arlington, VA 22313-1450.



IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Inventors: Jiping Li; Peter G. Borden; Edgar B. Genio  
Assignee: Applied Materials, Inc.  
Title: High Throughput Measurement Of Via Defects In Interconnects  
Serial No.: 10/813,407 Filing Date: March 29, 2004  
Examiner: Unknown Group Art Unit: 2811  
Docket No.: BOX016 US Confirmation No: 5642

Santa Clara, California  
March 23, 2005

MAIL STOP AMENDMENT  
COMMISSIONER FOR PATENTS  
P.O. BOX 1450  
ALEXANDRIA, VA 22313-1450

**INFORMATION DISCLOSURE STATEMENT  
UNDER 37 CFR §1.97(b)**

Dear Sir:

Pursuant to 37 C.F.R. § 1.56, §1.97 and §1.98, the Applicants submit for consideration in the above-identified patent application the documents listed on the accompanying Form PTO-1449. Copies of references numbered 47-96 are submitted herewith. The Examiner is requested to make these documents of record. The remaining references are not attached hereto, because these references are issued patents or publications which are readily available in the U.S. Patent and Trademark Office.

**In addition, Applicants submit for the Examiner's consideration, the prosecution histories of ten co-owned applications/patents, which are identified in the attached PTO-1449 as items 97-106.** The Applicants presume that the Examiner has access to and will review the cited applications/patents and the files thereof for any office actions, amendments or other materials that may be relevant to the patentability of the claims of the present application.

Citation of these prosecution histories (including the arguments against patentability advanced by Examiners in their respective Office Actions and the Applicants' arguments in

SILICON VALLEY  
PATENT GROUP LLP  
2350 Mission College Blvd.  
Suite 360  
Santa Clara, CA 95054  
(408) 982-8200  
FAX (408) 982-8210


the corresponding Amendments) is in accordance with the recent case DAYCO PRODUCTS, INC. v. TOTAL CONTAINMENT, INC., 02-1497, decided May 23, 2003 by the Court of Appeals for the Federal Circuit. The Examiner is presumed to be knowledgeable about the current case law, including the above-mentioned Dayco case. However, if the Examiner needs a copy of the Dayco case, please call the undersigned.

For any of the following U.S. patent application(s) cited in the attached PTO-1449 that are currently pending, the Applicants further presume that the Examiner will consider any **future** office actions, amendments or other materials in the file thereof that may be relevant to the patentability of the claims herein. **If the Applicants' understanding in this regard is not correct, please notify the undersigned so that copies of any such documents can be submitted to the Examiner.**


This Information Disclosure Statement is submitted pursuant to 37 CFR §1.97(b) as it is within three months of the filing date of a national application other than a continued prosecution application and/or before the mailing of a first Office Action on the merits. Accordingly, no fee is required.

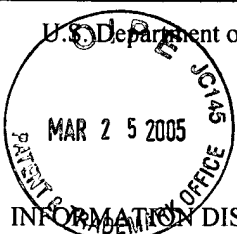
Applicants would appreciate the Examiner initialing and returning the Form PTO-1449, indicating that the information has been considered and made of record herein.

The information contained in this Information Disclosure Statement is to the best of my knowledge and is not to be construed as a representation that: (i) a complete search has been made; (ii) additional information material to the examination of this application does not exist; (iii) the information, protocols, results and the like reported by third parties are accurate or enabling; or (iv) the above information constitutes prior art to the subject invention.

|   |                       |
|---|-----------------------|
| <b>CERTIFICATE OF MAILING BY "FIRST CLASS"</b>  |                       |
| I hereby certify that this paper or fee is being deposited with the United States Postal Service with sufficient postage as first class mail in an envelope addressed to: Commissioner for Patents, P.O. Box 1450, Alexandria, VA 22313-1450 on the below date. |                       |
|    | <i>March 23, 2005</i> |
| Attorney for Applicant(s)   | Date of Signature     |

Respectfully submitted,

  
Omkar K. Suryadevara  
Attorney for Applicant(s)  
Reg. No. 36,320

|  |                       |                |
|--|-----------------------|----------------|
|  <p>U.S. Department of Commerce, Patent and Trademark Office</p> <p>INFORMATION DISCLOSURE STATEMENT BY APPLICANT</p> <p>(Use several sheets if necessary)</p> | Application No.:      | 10/813,407     |
|  | Filing Date:          | March 29, 2004 |
|  | First Named Inventor: | Jiping Li      |
|  | Group Art Unit:       | 2811           |
|  | Examiner Name:        | Unknown        |
|  | Confirmation No.:     | 5642           |
|  | Attorney Docket No.:  | BOX016 US      |

| U.S. Patent Documents |     |                    |          |                   |       |          |                               |
|-----------------------|-----|--------------------|----------|-------------------|-------|----------|-------------------------------|
| *Examiner<br>Initials |     | Document<br>Number | Date     | Name              | Class | Subclass | Filing Date if<br>Appropriate |
|                       | 1.  | 6,489,801          | 12/3/02  | Borden et al.     | 324   | 766      |                               |
|                       | 2.  | 6,812,047          | 11/2/04  | Borden et al.     | 438   | 16       |                               |
|                       | 3.  | 5,966,019          | 10/12/99 | Borden            | 324   | 752      |                               |
|                       | 4.  | 5,377,006          | 12/27/94 | Nakata            | 356   | 349      |                               |
|                       | 5.  | 6,323,951          | 11/27/01 | Borden et al.     | 356   | 502      |                               |
|                       | 6.  | 6,426,644          | 7/30/02  | Borden et al.     | 324   | 765      |                               |
|                       | 7.  | 5,042,951          | 8/27/91  | Gold et al.       | 356   | 369      |                               |
|                       | 8.  | 5,159,412          | 10/27/92 | Willenborg et al. | 356   | 445      |                               |
|                       | 9.  | 5,181,080          | 1/19/93  | Fanton et al.     | 356   | 381      |                               |
|                       | 10. | 5,228,776          | 7/20/93  | Smith et al.      | 374   | 5        |                               |
|                       | 11. | 4,255,971          | 3/17/81  | Rosencwaig        | 73    | 606      |                               |
|                       | 12. | 4,579,463          | 4/1/86   | Rosencwaig et al. | 374   | 57       |                               |
|                       | 13. | 4,632,561          | 12/30/86 | Rosencwaig et al. | 356   | 432      |                               |
|                       | 14. | 4,636,088          | 1/13/87  | Rosencwaig et al. | 374   | 5        |                               |
|                       | 15. | 4,750,822          | 6/14/88  | Rosencwaig et al. | 324   | 445      |                               |
|                       | 16. | 6,049,220          | 4/11/00  | Borden et al.     | 324   | 765      |                               |
|                       | 17. | 6,483,594          | 11/19/02 | Borden et al.     | 356   | 502      |                               |
|                       | 18. | 6,154,280          | 11/2/00  | Borden            | 356   | 376      |                               |
|                       | 19. | 6,054,868          | 4/25/00  | Borden et al.     | 324   | 752      |                               |
|                       | 20. | 5,883,518          | 3/16/99  | Borden            | 324   | 752      |                               |
|                       | 21. | 5,877,860          | 3/2/99   | Borden            | 356   | 376      |                               |
|                       | 22. | 5,978,074          | 11/2/99  | Opsal et al.      | 356   | 72       |                               |
|                       | 23. | 6,268,916          | 7/31/01  | Lee et al.        | 356   | 432      |                               |
|                       | 24. | 5,574,562          | 11/12/96 | Fishman et al.    | 356   | 432      |                               |
|                       | 25. | 6,169,601          | 1/2/01   | Eremin et al.     | 356   | 240      |                               |

|  |                  |
|--|------------------|
| Examiner:  | Date Considered: |
| <p>* Examiner: Initial if reference is considered, whether or not citation is in conformance with MPEP 609; Draw line through citation if not in conformance and not considered. Include copy of this form with your communication with applicant.</p> |                  |

|  |                       |                |
|--|-----------------------|----------------|
| U.S. Department of Commerce, Patent and Trademark Office<br><br>INFORMATION DISCLOSURE STATEMENT BY APPLICANT<br>(Use several sheets if necessary) | Application No.:      | 10/813,407     |
|  | Filing Date:          | March 29, 2004 |
|  | First Named Inventor: | Jiping Li      |
|  | Group Art Unit:       | 2811           |
|  | Examiner Name:        | Unknown        |
|  | Confirmation No.:     | 5642           |
|  | Attorney Docket No.:  | BOX016 US      |

|  |     |                |          |                   |     |     |  |
|--|-----|----------------|----------|-------------------|-----|-----|--|
|  | 26. | 3,803,413      | 4/9/74   | Vanzetti et al.   | 250 | 338 |  |
|  | 27. | 2002/0126732A1 | 9/12/02  | Shakouri et al.   | 374 | 130 |  |
|  | 28. | 6,327,035      | 12/4/01  | Li et al.         | 356 | 432 |  |
|  | 29. | 6,281,027      | 9/28/01  | Wei et al.        | 438 | 14  |  |
|  | 30. | 4,950,990      | 8/21/90  | Moulder           | 324 | 224 |  |
|  | 31. | 4,521,118      | 06/00/85 | Rosencwaig        | 374 | 5   |  |
|  | 32. | 5,074 669      | 12/1/91  | Opsal             | 356 | 447 |  |
|  | 33. | 3,909,602      | 9/30/75  | Micka             | 716 | 4   |  |
|  | 34. | 5,790,251      | 8/4/98   | Hagiwara          | 356 | 351 |  |
|  | 35. | 4,634,290      | 1/6/87   | Rosencwaig        | 374 | 5   |  |
|  | 36. | 4,522,510      | 6/11/85  | Rosencwaig        | 374 | 7   |  |
|  | 37. | 4,455,741      | 6/26/84  | Kolodner          | 29  | 574 |  |
|  | 38. | 4,466,748      | 8/21/84  | Needham           | 374 | 129 |  |
|  | 39. | 4,795,260      | 1/3/89   | Schuur et al.     | 356 | 400 |  |
|  | 40. | 6,559,942      | 5/6/03   | Sui et al.        | 356 | 369 |  |
|  | 41. | 6,528,333      | 3/4/03   | Jun et al.        | 438 | 16  |  |
|  | 42. | 3,462,602      | 8/16/67  | Apple             | 250 | 83  |  |
|  | 43. | 5,149,978      | 9/22/92  | Opsal et al.      | 250 | 234 |  |
|  | 44. | 6,400,454      | 6/4/02   | Noguchi et al.    | 356 | 237 |  |
|  | 45. | 4,679,946      | 7/14/87  | Rosencwaig et al. | 374 | 5   |  |
|  | 46. | 6,694,284 B1   | 2/17/04  | Nikoonahad et al. | 702 | 155 |  |

## Foreign Patent Documents

|  |     |              |          |         |       |          | Translation |    |
|--|-----|--------------|----------|---------|-------|----------|-------------|----|
|  |     | Document     | Date     | Country | Class | Subclass | Yes         | No |
|  | 47. | 0 718 595    | 20.12.95 | EP      | G01B  | 6-Nov    |             |    |
|  | 48. | 2000 009443A | Jan-00   | JP      | G01B  |          |             |    |
|  | 49. | 405006929A   | Jan-93   | JP      | H01L  | 21/66    |             |    |

Examiner:

Date Considered:

\* Examiner: Initial if reference is considered, whether or not citation is in conformance with MPEP 609; Draw line through citation if not in conformance and not considered. Include copy of this form with your communication with applicant.

|  |                       |                |
|--|-----------------------|----------------|
| U.S. Department of Commerce, Patent and Trademark Office<br><br>INFORMATION DISCLOSURE STATEMENT BY APPLICANT<br>(Use several sheets if necessary) | Application No.:      | 10/813,407     |
|  | Filing Date:          | March 29, 2004 |
|  | First Named Inventor: | Jiping Li      |
|  | Group Art Unit:       | 2811           |
|  | Examiner Name:        | Unknown        |
|  | Confirmation No.:     | 5642           |
|  | Attorney Docket No.:  | BOX016 US      |

|  |     |  |            |    |      |       |  |  |
|--|-----|--|------------|----|------|-------|--|--|
|  | 50. | ISR PCT/<br>US99/12999   | 09.06.1999 | WO | G01L | 21/17 |  |  |
|  | 51. | ISR<br>PCT/US03/06239  | 02.28.2003 | WO | G01L | 21/55 |  |  |
|  | 52. | ISR<br>PCT/US01/07475  | 07.03.2001 | WO |      |       |  |  |
|  | 53. | ISR<br>PCT/US03/06379  | 02.28.2003 | WO | G01N | 21/88 |  |  |
| Other Art (Including Author, Title, Date, Pertinent Pages, Etc.) |     |  |            |    |      |       |  |  |
|  | 54. | Paquin, "Properties of Metals", Handbook of Optics, Vol. II, McGraw-Hill, Inc. (month unavailable), 1995, pp. 35.3-35.7  |            |    |      |       |  |  |
|  | 55. | Rosencwaig et al. "Detection of Thermal Waves Through Optical Reflectance", Appl Phys. Lett. 46, June 1985, pp1013-1015  |            |    |      |       |  |  |
|  | 56. | Rosencwaig, "Thermal-Wave Imaging", SCIENCE, Volume 218, No. 4569, Oct. 1982, pp.223-228   |            |    |      |       |  |  |
|  | 57. | Opsal et al. "Thermal-Wave Detection and Thin-Film Thickness Measurements with Laser Beam Deflection", Applied Optics, Vol. 22, No. 20, Oct. 1983, pp. 3169-3176   |            |    |      |       |  |  |
|  | 58. | Rosencwaig, "Thermal Wave Characterization and Inspection of Semiconductor Materials and Devices", Chapter 5 (pp. 97-135) of Photoacoustic and Thermal Wave Phenomena in Semiconductors, North Holland (month unavailable) 1987  |            |    |      |       |  |  |
|  | 59. | J. Opsal, "High Resolution Thermal Wave Measurements and Imaging of Defects and Damage in Electronic Materials" Photoacoustic and Photothermal Phenomena II, Springer Series in Optical Sciences, Vol. 62, Springer Verlag Berlin, Heidelberg, (month unavailable) 1990. |            |    |      |       |  |  |
|  | 60. | J. Kolzer et al "Thermal Imaging and Measurement Techniques for Electronic Materials and Devices" Microelectronic Engineering, vol. 31, 1996 (month unknown) pages 251-270   |            |    |      |       |  |  |
|  | 61. | C. Martinsons et al. "Recent progress in the measurement of thermal properties of hard coatings" Thin Solid Films, vol. 317, April 1998, 455-457.  |            |    |      |       |  |  |
|  | 62. | S. Wolf and R. N. Tauber, "Silicon Processing For The VLSI Era", Volume 1, 1986, pages 388-399   |            |    |      |       |  |  |
|  | 63. | Yaozhi Hu and Sing Pin Tay, "Spectroscopic ellipsometry investigation of nickel silicide formation by rapid thermal process", J. Vac. Sci. Technology, American Vacuum Soc. May/Jun 1998, pages 1820-1824  |            |    |      |       |  |  |
|  | 64. | Bristow, Thomas C. and Dag Lindquist, "Surface Measurements With A Non-Contact Nomarski-Profilng Instrument", Interferometric Metrology, SPIE vol. 816, August 1987, pages 106-110   |            |    |      |       |  |  |
|  | 65. | Charles Kittel, "Introduction to Solid State Physics", Fourth Edition, John Wiley & Sons, published prior to March 1, 2002, pages 262-264  |            |    |      |       |  |  |
|  | 66. | Rolf E. Hummel, "Electronic Properties of Materials, An Introduction For Engineers", published prior to March 1, 2002, pages 137-145   |            |    |      |       |  |  |
|  | 67. | H.S. Carslaw and J.C. Jaeger, "Conduction of Heat In Solids", Second Edition, published prior to March 1, 2002, pages 64-66  |            |    |      |       |  |  |
|  | 68. | A. Rosencwaig, "Thermal Wave Measurement of Thin-Film Thickness", 1986 American Chemical Society, pp.182-191   |            |    |      |       |  |  |

Examiner:

Date Considered:

\* Examiner: Initial if reference is considered, whether or not citation is in conformance with MPEP 609; Draw line through citation if not in conformance and not considered. Include copy of this form with your communication with applicant.

|  |                       |                |
|--|-----------------------|----------------|
| U.S. Department of Commerce, Patent and Trademark Office<br><br>INFORMATION DISCLOSURE STATEMENT BY APPLICANT<br>(Use several sheets if necessary) | Application No.:      | 10/813,407     |
|  | Filing Date:          | March 29, 2004 |
|  | First Named Inventor: | Jiping Li      |
|  | Group Art Unit:       | 2811           |
|  | Examiner Name:        | Unknown        |
|  | Confirmation No.:     | 5642           |
|  | Attorney Docket No.:  | BOX016 US      |

|     |  |
|-----|--|
| 69. | A. Rosencwaig et al., "Thin-Film Thickness Measurements with Thermal Waves", Journal De Physique, October 1983, pp. C6-483 - C6-489  |
| 70. | S. Ameri et al., "Photo-Displacement Imaging", March 30, 1981, pp. 337-338   |
| 71. | L. Chen et al., "Thermal Wave Studies of Thin Metal Films Using the Meta-Probe-A New Generation Photothermal System" 25th Review of Progress in QNDE, Snowbird, UT 19-24 July, 1998, pp 1-12   |
| 72. | P. Alpern and S. Wurm, "Modulated Optical Reflectance Measurements on Bulk Metals and Thin Metallic Layers", J. Appl. Phys. 66(4), 15 August 1989, pp 1676-1679  |
| 73. | J. Opsal, "The Application of Thermal Wave Technology to Thickness and Grain Size Monitoring of Aluminum Films", SPIE Vol. 1596 Metalization Performance and Reliability Issues for VLSI and ULSI (1991), pp 120-131                         |
| 74. | A. Rosenwaig, "Process Control In IC Manufacturing With Thermal Waves", Review of Progress in Quantitative Nondestructive Evaluation, Vol.9, 1990, pp 2031-2037  |
| 75. | K. Farnaam, "Measurement of Aluminum Alloy Grain Size on Product Wafers and its Correlation to Device Reliability", 1990 WLR Final Report, pp 97-106   |
| 76. | B.C. Forget et al., "High Resolution AC Temperature Field Imaging", Electronic Letters 25th September 1997, Vol. 33 No. 20, pp 1688-1689   |
| 77. | C. Paddock et al., "Transient Thermoreflectance from Metal Films", May 1986 Vol. 11, No. 5 Optical Letters, pp 273-275   |
| 78. | C. Paddock et al., "Transient Thermoreflectance from Metal Films", J. Appl. Phys. 60(1), 1 July 1986, pp 285-290   |
| 79. | Per-Eric Nordail et al. "Photothermal Radiometry", Physica Scripta, Vol. 20, 659-662, 1979   |
| 80. | A. Rosenwaig, "Thermal Wave Monitoring and Imaging of Electronic Materials and Devices", pp 73-109   |
| 81. | A. Rosenwaig, "Applications of Thermal-Wave Physics to Microelectronics", VLSI Electronics, Microstructure Science Vol. 9, 1995, pp 227-288  |
| 82. | W. Lee Smith et al., "Voids, Notches and Microcracks in Al Metallization Detected by Nondestructive Thermal Wave Imaging", June 23m 1989, pp. 211-221  |
| 83. | W. Lee Smith et al., "Imaging of Subsurface Defects in ULSI Metalization (Al Voids SI Preciptates, Silicide Instability) and SI Substrates (D Defects), Technical Proceedings Simicon/Japan 1992, Nippon Convention Center, Japan pp 238-246 |
| 84. | W. Lee Smith, "Nondestructive Thermal Wave Imaging of Voids & Microcracks in Aluminum Metallization", 1989 WLR Final Report, pp 55-68  |
| 85. | W. Lee Smith, "Direct Measurement of Stress-Induced Void Growth by Thermal Wave Modulated Optical Reflectance Imaging", 1991 IEEE/IRPS, pp 200-208   |
| 86. | W. Lee Smith, "Evaluating Voids and Microcracks in Al Metalization", Semiconductor International, January 1990, pp 232 -237  |
| 87. | C. G. Welles et al., "High-Resolution Thermal Wave Imaging of Surface and Subsurface Defects in IC Metal Lines", Materials Research Society, SF Marriott, April 27-May 1, 1992, pp 1187-1191   |

|   |                  |
|---|------------------|
| Examiner:   | Date Considered: |
| * Examiner: Initial if reference is considered, whether or not citation is in conformance with MPEP 609; Draw line through citation if not in conformance and not considered. Include copy of this form with your communication with applicant. |                  |

|  |                       |                |
|--|-----------------------|----------------|
| U.S. Department of Commerce, Patent and Trademark Office<br><br>INFORMATION DISCLOSURE STATEMENT BY APPLICANT<br>(Use several sheets if necessary) | Application No.:      | 10/813,407     |
|  | Filing Date:          | March 29, 2004 |
|  | First Named Inventor: | Jiping Li      |
|  | Group Art Unit:       | 2811           |
|  | Examiner Name:        | Unknown        |
|  | Confirmation No.:     | 5642           |
|  | Attorney Docket No.:  | BOX016 US      |

|      |  |
|------|--|
| 88.  | J. A. Batista et al., "Biased MOS-FET and Polycrystalline Silicon Tracks Investigated by Photothermal Reflectance Microscopy", pp 468-469        |
| 89.  | L. Chen et al., "Meta-Probe: A New Generation Photothermal System For Thin Metal Films Characterization" (believed to be prior to March 1, 2002) |
| 90.  | L. Chen et al., "Thermal Wave Studies of Thin Metal Films and Structures", (believed to be prior to March 1, 2002)                               |
| 91.  | 9th International Conference on Photoacoustic and Photothermal Phenomena Conference Digest, June 27-30, 1996 Nanjing, P.R. China, pp 81          |
| 92.  | R. S. Sharpe, "Research Techniques in Nondestructive Testing Vol. VII, Academic Press 1984, pp 158-365   |
| 93.  | R. L. Thomas et al., "Thermal Wave Imaging For Nondestructive Evaluation" 1982 Ultrasonic Symposium, pp 586-590                                  |
| 94.  | G. Slade Cargill III, "Electron-Acoustic Microscopy", Physics Today, October 1981, pp 27-32  |
| 95.  | A. Rosencwaig, "Thermal Wave Microscopy", Solid State Technology, March 1982, pp 91-97   |
| 96.  | Eric A. Ash, "Acoustical Imaging" Volume 12, Plenum Press, July 19-22, 1982, pp 61-65  |
| 97.  | US Appl. No. 09/095,805 entitled "Apparatus and Method For Measuring A Property of a Layer in a Multilayered Structure"                          |
| 98.  | US Appl. No. 10/722,724 entitled "Apparatus and Method For Measuring A Property of a Layer in a Multilayered Structure"                          |
| 99.  | US Appl. No. 10/090,316 entitled "Apparatus and Method For Measuring A Property Of A Layer In A Multilayered Structure"                          |
| 100. | US Appl. No. 09/521,232 entitled "Evaluating A Property Of A Multilayered Structure"   |
| 101. | US Appl. No. 10/977,380 entitled "Evaluating A Property Of A Multilayered Structure"   |
| 102. | US Appl. No. 09/788,273 entitled "Evaluating Sidewall Coverage In A Semiconductor Wafer"   |
| 103. | US Appl. No. 10/090,262 entitled "Evaluating A Multilayered Structure For Voids"   |
| 104. | US Appl. No. 10/984,463 entitled "Evaluating A Multilayered Structure For Voids"   |
| 105. | US Appl. No. 10/090,287 entitled "Identifying Defects In A Conductive Structure Of A Wafer, Based On Heat Transfer Therethrough"                 |
| 106. | US Appl. No. 10/979,397 entitled "Evaluation Of Openings In A Dielectric Layer"  |

|   |                  |
|---|------------------|
| Examiner:   | Date Considered: |
| * Examiner: Initial if reference is considered, whether or not citation is in conformance with MPEP 609; Draw line through citation if not in conformance and not considered. Include copy of this form with your communication with applicant. |                  |